12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN20251003000.1
Qualification of additional Assembly sites for select SOIC devices
Change Notification / Sample Request

Date: October 03, 2025
To: SCHLUMBERGER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20251003000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM193DRG4	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN#20251003000.1	**PCN Date:**	October 03, 2025
Title:	Qualification of additional Assembly sites for select SOIC devices		
Customer Contact:	Change Management Team	**Dept:**	Quality Services
Proposed 1st Ship Date:	January 01, 2026	**Sample requests accepted until:**	December 02, 2025*

***Sample requests received after December 02, 2025 will not be supported.**

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction information and all assembly sites are as follows:

SOIC Build sites	
Assembly Sites	TIEMA, TAI, FMX, MLA, HFTF
Mold Compound	4211880 4212090 4209640 4221499 4230910 SID#R-30 8095179
Mount Compound	4147858 4205846 411470 4208458 SID# A-03 4111062 4213245
Lead Frame Finish	NiPdAu, Sn
Bond Wire	Cu, Au

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
MLA	MLA	MYS	Kuala Lumpur
FMX	MEX	MEX	Aguascalientes
TAI	TAI	TWN	Chung Ho, New Taipei City
HFTF	HFT	CHN	Hefei
TIEM	GNZ	MYS	Melaka

Sample product shipping label (not actual product label)

Product Affected:

LF347BDR	LM393ADR	TL074HIDR	TL084CDR
LF347DR	LM393DR	TL074HIDRG4	TL084HIDR
LF353DR	SN1605025DR	TL074IDR	TL084IDR
LM193DR	TL072CDR	TL074IDRE4	TL084QDR
LM193DRG4	TL072HIDR	TL074IDRG4	TLV9062IDR
LM2903AVQDR	TL072IDR	TL082ACDR	TLV9062IDRG4
LM2903DR	TL074ACDR	TL082CDR	TLV9064IDR
LM2903DR-S	TL074BCDR	TL082HIDR	TSV914AIDR
LM2903VQDR	TL074BCDRE4	TL082IDR	TSV914AIDRG4
LM293ADR	TL074BCDRG4	TL084ACDR	
LM293DR	TL074CDR	TL084BCDR	

SOIC Qualification Report

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	FMX TL494ID	TIEMA DS90LV019TMX LM6172IM/NOPB UCC21330BQDRQ1
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C	1000 hours	-	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	-
AC	Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (TPS2048AD)	3/66/0 (Note a)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	MLA MAX232D	TAI TPIC6C596DRQ1 ISO7221CD
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
AC	Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (L358BID)	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	HFTAT SN74HCS74D
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 hours	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0
MQ	Manufacturability	-	Pass

Devices TL494ID, SN74HCS74D, DS90LV019TMX, MAX232D, SN74HCS74D, ISO7221CD, LM6172IM/NOPB are qualified at MSL1, 260C.
UCC21330BQDRQ1 qualified at MSL3, 260C.
Note a – Solderability data collected on LMP8601EDRQ1, LM6172IM, and UCC21330BQDRQ1
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable
- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and

assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.